



ASSP, 42V, 1A, Synchronous Buck-boost DC/DC Converter IC

S6BP201A is a 1-Ch Buck-boost DC/DC converter IC with four built-in switching FETs. This IC is able to supply up to 1.0A of load current within the very wide range from 2.5V to 42V in the input voltage. This IC has an operation mode that is automatically changed to PFM operation during low load, which can achieve super-high efficiency with a very low quiescent current 20 µA. It is possible to provide stable output voltage from an automotive cold cranking and load dump, up to 42V, conditions within 1 ms transition time. As a result, this IC is suitable for power supply solutions of automotive and Industrial applications. This IC has the SYNC function, which is capable of selecting the SYNC_IN that is able to inputs an external clock signal. When an external clock signal in the range from 200 kHz is inputted, the FETs perform the switching operation with synchronizing signal from an external clock. When an external clock signal is not inputted, the FETs perform the switching operation from an internal clock. The internal clock signal in the range from 200 kHz to 2.1 MHz can be set by an external resistor. Since external voltage setting resistors and phase compensation capacitors are not required with this IC, it can reduce the number of parts and a part mounting area. This IC has five protection (output OVP), output over current protection (output UVLO), output under voltage protection (output UVP), output over voltage protection (output OVP), output over current protection (output OCP), and thermal shutdown (TSD). Moreover, this IC has the power good (PG) function that indicates the state of the output voltage (VOUT pin). When the output voltage reaches the PG voltage, the PG signal is outputted. The VOUT output voltage of this product is selectable from the product lineup (refer to the "1. Product Lineup").

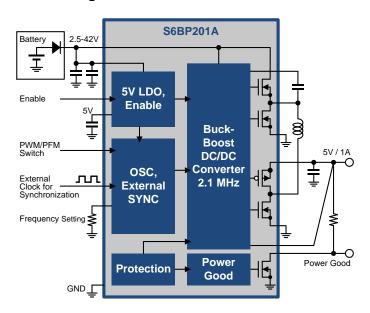
Features

- ■Wide input voltage range: 2.5V to 42V
- Selectable output voltage (factory settable): 5.000V/5.050V/5.075V/5.100V/5.125V/5.150V/5.200V
- ■Wide operating frequency range: 200 kHz to 2.1 MHz
- ■External synchronized clock range: 200 kHz to 400 kHz
- ■SYNC function
 - □ SYNC_IN: External clock input (Unless inputting clock, this IC operates by internal clock)
- ■Super-high efficiency by PFM operation (When setting MODE pin to a low level)
- Automatic PWM/PFM switching operation and fixed PWM operation are selectable by MODE pin
- ■Built-in switching FET
- Synchronous current mode architecture
- Shutdown current: Lower than 1 µA
- Quiescent current: 20 µA
- ■Power Good Monitor
 - □ Output voltage monitoring by window comparator
 - □ Power-on reset time: 14 ms
- Soft start time without load dependence : 0.9 ms (When switching frequency = 2.1 MHz)
- ■Enhanced protection functions
 - □ Input under voltage lockout
 - □ Output under voltage protection: 95.5%
 - □ Output over voltage protection: 104.5%
 - □ Output over current protection
 - □ Thermal shutdown
- ■Small ETSSOP16 package (exposed PAD): 5 mm × 6.4 mm
- ■AEC-Q100 compliant (Grade-1)

Applications

- ■Body Control Module (BCM)
- ■Gateway module
- ■Automotive applications
- ■Industrial applications

Block Diagram





More Information

Cypress provides a wealth of data at www.cypress.com/pmic to help you to select the right PMIC device for your design, and to help you to quickly and effectively integrate the device into your design. Following is an abbreviated list for S6BP201A.

- Overview: Automotive PMIC Portfolio, Automotive PMIC Roadmap
- Product Selector:
 - □ S6BP201A:
 - 1-Ch Buck-Boost Automotive PMIC
- Application Notes: Cypress offers S6BP201A application notes. Recommended application notes for getting started with S6BP201A are:
 - □ AN99497: Designing a Power Management System with S6BP201A, S6BP202A, and S6BP203A
 - □ AN201006: Thermal Considerations and Parameters

- ■Evaluation Kit Operation Manual:
 - □ S6SBP201A1AVA1001:

Power block of automotive instrument cluster

- ■Related Products:
 - □ S6BP202A, S6BP203A:
 - 1-Ch Buck-Boost Automotive PMIC
 - □ S6BP401A:
 - 6-Ch Automotive PMIC for ADAS
 - □ S6BP501A, S6BP502A:
 - 3-Ch Automotive PMIC for Instrument Cluster



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1. Product Lineup

The VOUT output voltage of this product is set at the factory shipment. To order a product, select an item from the product lineup blow.

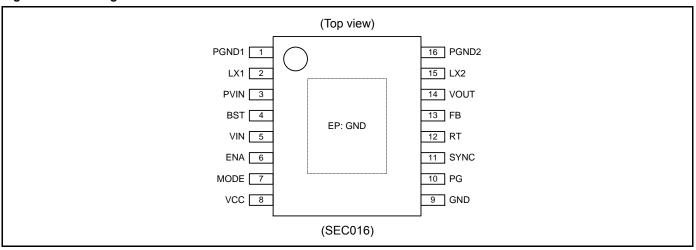
	Order	Order	Ordor	Order	Order	Order	VOUT Output	SYNC	VOUT UVP Threshold [%]		VOUT OVP Threshold [%]		
Part Number (MPN)	Code	Voltage [V]	Function	Falling (Typ)	Rising (Typ)	Rising (Typ)	Falling (Typ)	Reset Time[s]					
S6BP201A1AST2B00A	1A	5.000	SYNC_IN	SYNC_IN	SYNC_IN								
S6BP201A2AST2B00A	2A	5.050											
S6BP201A3AST2B00A	3A	5.075							ļ ļ				
S6BP201A4AST2B00A	4A	5.100				95.5	96.5	104.5	103.5	14.0m			
S6BP201A5AST2B00A	5A	5.125								I			
S6BP201A6AST2B00A	6A	5.150											
S6BP201A7AST2B00A	7A	5.200											

MPN: Marketing Part Number



2. Pin Assignment

Figure 2-1 Pin Assignment



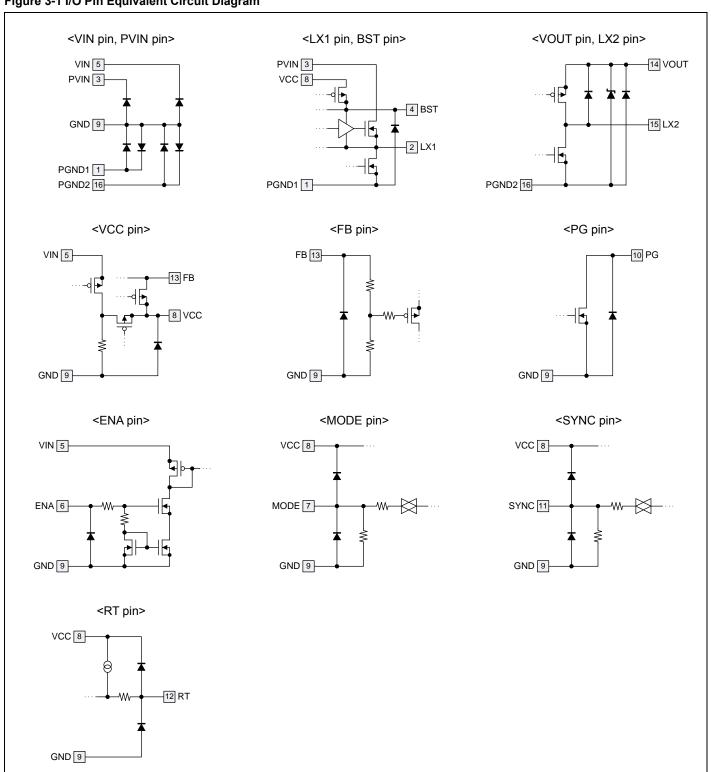
3. Pin Descriptions

Table 3-1 Pin Descriptions

Pin No.	Pin Name	I/O	Description			
1	PGND1	-	GND pin for built-in switching FET			
2	LX1	0	Inductor connection pin			
3	PVIN	ı	Power supply pin for PWM controller and switching FETs			
4	BST	ı	BST(Boost) capacitor connection pin			
5	VIN	ı	Power supply pin			
6	ENA	ı	DC/DC converter enable pin			
7	MODE	- 1	PWM/PFM operation control pin			
1	MODE	'	For the MODE pin setting, refer to "10.1 Setting the Operation Conditions"			
8	VCC	0	LDO output pin of Internal reference voltage			
0	VCC	0	VCC capacitor connection pin			
9	GND	-	GND pin			
10	PG	0	Open drain output pin for power good. When being used, connect PG pin to VCC pin or			
10	1.0	0	VOUT pin. When not being used, leave PG pin open.			
11	SYNC	SYNC	SYNC	11 SYNC	1	External clock input pin. For the SYNC pin setting, refer to "10.1 Setting the Operation
• •	01110	'	Conditions"			
12	RT	0	Timing resistor connection pin for internal clock (switching frequency)			
			For the resistance, refer to "10.1 Setting the Operation Conditions"			
13	FB	l	Output voltage feedback pin			
14	VOUT	0	DC/DC converter output pin			
15	LX2	0	Inductor connection output pin.			
16	PGND2	-	GND pin for built-in switching FET			
EP	GND	-	GND pin			



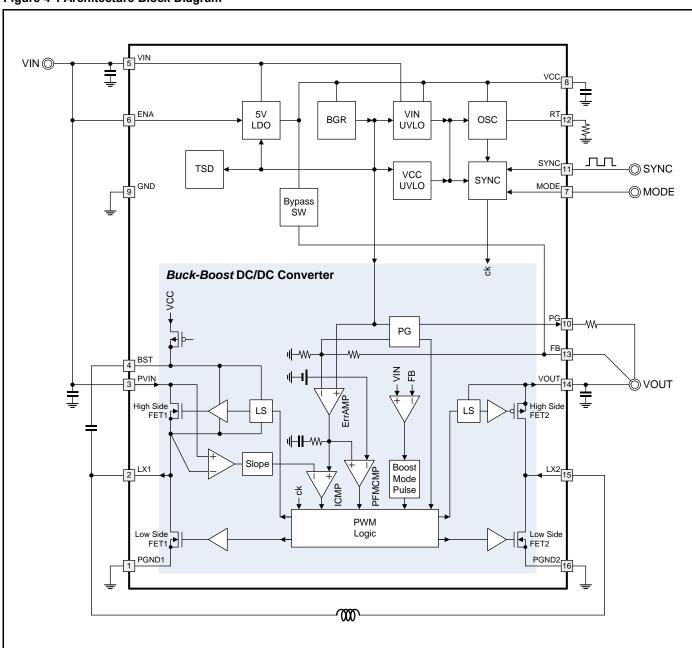
Figure 3-1 I/O Pin Equivalent Circuit Diagram





4. Architecture Block Diagram

Figure 4-1 Architecture Block Diagram





5. Absolute Maximum Ratings

Parameter	Symbol	Condition	Ra	Rating			
Parameter	Syllibol	Condition	Min	Max	Unit		
	V_{VIN}	VIN pin	-0.3	+48.0	V		
Power supply voltage (*1)	V_{PVIN}	PVIN pin	-0.3	+48.0	V		
	Vvcc	VCC pin	-0.3	+6.9	V		
	V_{BST}	BST pin	-0.3	+48.0	V		
	V_{LX1}	LX1 pin	-2.0	+48.0	V		
	V_{LX2}	LX2 pin	-2.0	+6.9	V		
	V_{FB}	FB pin	-0.3	Vvcc	V		
Terminal voltage (*1)	V_{RT}	RT pin	-0.3	Vvcc	V		
	V _{MODE}	MODE pin	-0.3	Vvcc	V		
	V _{SYNC}	SYNC pin	-0.3	Vvcc	V		
	V_{ENA}	ENA pin	-0.3	+48.0	V		
	V_{PG}	PG pin	-0.3	+6.9	V		
Difference voltage (*1)	V_{BST-LX}	Between BST-LX1 pins	-0.3	+6.9	V		
Difference voltage (*1)	V_{GND}	Between GND-PGND1 pins, Between GND-PGND2 pins	-0.3	+0.3	V		
PG output current	I_{PG}	PG pin	-3	0	mA		
Power dissipation (*1)	P _D	Ta ≤ ±25°C	0	3324 (*2)	mW		
Storage temperature	T_{STG}	-	- 55	+150	°C		

^{*1:} When PGND1 = PGND2 = GND = 0V

Warning:

6. Recommended Operating Conditions

Parameter	Cumbal	Condition			Value		Unit
Parameter	Symbol		Condition			Max	Offic
Dower cumply voltage (*1)	17	\/INI nin	At start-up	5.0	12.0	42.0	V
Power supply voltage (*1)	V_{VIN}	VIN pin	After start-up	2.5	12.0	42.0	V
	V _{BST}	BST pin		0.0	-	47.5	V
	V _{LX1}	LX1 pin		-1.0	+12.0	+42.0	V
	V _{LX2}	LX2 pin		-1.0	-	+5.5	V
Torminal valtage (*1)	V_{FB}	FB pin		0.0	-	5.5	V
Terminal voltage (*1)	V _{MODE}	MODE pin			-	5.5	V
	V_{SYNC}	SYNC pin	0.0	-	5.5	V	
	V_{ENA}	ENA pin	0.0	12.0	42.0	V	
	V_{PG}	PG pin	0.0	-	5.5	V	
	V _{BST-LX1}	Between BST-	0.0	-	5.5	V	
Difference voltage (*1)	V_{GND}		D-PGND1 pins, D-PGND2 pins	-0.05	0.00	+0.05	V
PG output current	l _{PG}	PG pin (sink c	current)	0	-	1	mA
BST capacitance	C _{BST}	Between BST-	Between BST-LX1 pins		0.100	0.470	μF
VCC capacitance	Cvcc	Between VCC	Between VCC-GND pins			10.0	μF
Timing resistance	R _{RT}	Between RT-0	Between RT-GND pins. When using internal clock			270	kΩ
Operating ambient Temperature	Та		-	-40	+25	+125	°C

^{*1:} When PGND1 = PGND2 = GND = 0V

Warning:

- 1. The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.
- 2. Any use of semiconductor devices will be under their recommended operating condition.
- 3. Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.
- 4. No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

Document Number: 002-08537 Rev. *C

^{*2:} When the product is mounted on 76.2 mm × 114.3 mm, four-layer FR-4 board

^{1.} Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.



7. Electrical Characteristics

VIN=PVIN=12V, ENA=5V

(Unless specified otherwise, these are the electrical characteristics under the recommended operating environment.)

Parameter		Symbol	Condition			Uni	
	i didiliotoi	<u> </u>		Min	Тур	Max	
			I _{VOUT} = 0A, When V _{VOUT} = 5.000 (*1)	4.925	5.000	5.075	V
			$I_{VOUT} = 0A$, When $V_{VOUT} = 5.050$ (*1)	4.975	5.050	5.125	V
			$I_{VOUT} = 0A$, When $V_{VOUT} = 5.075$ (*1)	4.999	5.075	5.151	V
	VOUT output voltage	V_{VOUT}	$I_{VOUT} = 0A$, When $V_{VOUT} = 5.100$ (*1)	5.024	5.100	5.176	V
			$I_{VOUT} = 0A$, When $V_{VOUT} = 5.125$ (*1)	5.048	5.125	5.201	V
			$I_{VOUT} = 0A$, When $V_{VOUT} = 5.150$ (*1)	5.073	5.150	5.227	V
			$I_{VOUT} = 0A$, When $V_{VOUT} = 5.200$ (*1)	5.122	5.200	5.278	V
Buck-boost	FB input resistance	R _{FB}	EN = 0V, Ta = +25°C	3.84	4.80	5.76	МΩ
DC/DC		RHSIDEFET1	LX1 = -30 mA (Between PVIN-LX1)	-	150	_	mΩ
converter	Switching FET	RLSIDEFET1	LX1 = 30 mA (Between LX1-PGND1)	-	150	_	mΩ
Block	on-resistance	RHSIDEFET2	LX2 = -30 mA (Between VOUT-LX2)	-	150	_	mΩ
		R _{LSIDEFET2}	LX2 = 30 mA (Between LX2-PGND2)	-	150	_	mΩ
	Switching FET leakage current	I _{LEAK}	-	-	_	5	μΑ
	Soft-start time	Tss	R_{RT} = 22 k Ω	0.855	0.9	0.945	ms
	Maximum output current	I_{VOUT}	PVIN ≥ 7.5V, Ta = 25°C	1.0 (*2)	-	_	Α
		10001	PVIN = 4.5V, Ta = 25°C	1.0 (*2)	-	-	Α
	Current limit	ILIMT	PVIN = 12V, L = 2.2µH	1.0 (*2)	-	-	Α
5V LDO block	VCC output voltage	V_{VCC}	VIN = 12V	4.9	5.0	5.1	٧
VIN UVLO	VIN UVLO falling threshold	$V_{\text{UVLOVINHL}}$	VIN input voltage when falling	2.30	2.40	2.50	٧
block	VIN UVLO rising threshold	Vuvlovinlh	VIN input voltage when rising	4.55	4.75	4.95	V
VCC UVLO	VCC UVLO falling threshold	Vuvlovcchl	VCC input voltage when falling	2.30	2.40	2.50	٧
block	VCC UVLO rising threshold	Vuvlovcclh	VCC input voltage when rising	4.55	4.75	4.95	V
	Enable condition	V_{ENA}			-	V_{VIN}	V
ENA pin	Enable condition	V_{DSB}	Disable voltage range	0.0	-	0.2	V
	ENA input current	I _{ENA}	V _{ENA} = 12V	-	1	3	μΑ
MODE pin	MODE input voltage	V _{MODE_L}	Automatic PWM/PFM switching operation	0.0	-	0.4	V
MODE bill		V_{MODE_H}	Fixed PWM operation	2.0	-	V_{VOUT}	٧
	MODE Input current	I _{MODE}	MODE = 5.0V	-	5	10	μA
OSC block	Switching frequency	Fosc	$R_{RT} = 22 k\Omega$	2.0	2.1	2.2	MHz
OSC DIOCK	Switching frequency		R_{RT} = 270 k Ω	180	200	220	kHz
	SYNC input threshold	V_{SYNC_L}	-	0.0	-	0.4	V
SYNC block	3110 lilput tillesilola	V_{SYNC_H}	_	2.0	-	V_{VOUT}	V
(SYNC_IN)	SYNC input frequency	V _{SYNC_L}	_	200	-	400	kHz
(01110_111)	SYNC input duty ratio	V _{SYNC_H}	_	+20	+50	+80	%
	SYNC leakage current	ILKSYNC	$V_{SYNC} = 5.0V$	-	5	10	μΑ
	VOUT UVP falling threshold	PGUVPHL	Falling threshold for VOUT output voltage setting (*1)	94.0	95.5	97.0	%
	VOUT UVP rising threshold	P _{GUVPLH}	Rising threshold for VOUT output voltage setting (*1)	95.0	96.5	98.0	%
DO 511-	VOUT OVP rising threshold	P _{GOVPLH}	Rising threshold for VOUT output voltage setting (*1)	103.0	104.5	106.0	%
PG block (UVP, OVP)	VOUT OVP falling threshold	PGOVPHL	Falling threshold for VOUT output voltage setting (*1)	102.0	103.5	105.0	%
	Leak current	I _{LKPG}	$V_{PWRGD} = 5.0V, V_{ENA} = 0V$	0	_	1	μΑ
	Low level output voltage	Volpg	I _{PGSINK} = 1 mA	0.025	0.05	0.15	V
	Delay time at abnormal detection	T_{PPG}	At power shutdown	-	7 (*2)	12 (*2)	μs
	Power-on reset time (*1)	T_{RPG}	At power good	9.1	14.0	18.9	ms



Parameter		Cumbal	Symbol Condition		Value			
	Parameter				Тур	Max	Unit	
Thermal		T _{TSDH}	-	ı	165 (*2)	-	°C	
shutdown block (TSD)	Shutdown temperature	T _{TSDL}	Hysteresis	ı	10 (*2)	-	°C	
	Shutdown current	I _{VINSDN}	VIN input current, V _{ENA} = 0V	-	1	5	μA	
Supply current	Quiescent current	Ivinq	VIN input current, V _{ENA} = 12V, I _{VOUT} = 0A, MODE/SYNC/PG Pins = OPEN	ı	20	40	μА	

^{*1:} Refer to "1. Product Lineup"

8. Functional Description

8.1 Protection Function

Input Under Voltage Lockout (Input UVLO)

The input UVLO is the function that prevents a malfunction of this IC from the following status, and protects poststage devices.

- □ Transitional state at start-up
- ☐ Momentary drop of power supply voltage

To prevent such a malfunction, this protection monitors the VIN input voltage and VCC voltage. When either VIN or VCC voltage falls to the UVLO falling threshold, 2.4V (Typ), or lower, the IC stops the VOUT voltage output and becomes UVLO status. When both VIN and VCC voltages reach the UVLO rising threshold, 4.75V (Typ), or higher, the IC is released from the UVLO state and returns to the normal operation.

Output Under Voltage Protection (Output UVP)

The output UVP is the function that monitors the voltage drop of the VOUT pin and notifies by the PG pin.

When the output voltage falls to the UVP falling threshold (P_{GUVPHL}) for the output voltage setting or lower, the PG voltage is fixed to the low level. The IC becomes the UVP status, but the switching operation is maintained under the UVP status.

When the output voltage once again reaches the UVP rising threshold (PGUVPLH) for the output voltage setting or higher, the IC is released from the UVP state and the PG voltage is fixed to the high level.

Output Over Voltage Protection (Output OVP)

The output OVP is the function that monitors the voltage rise of the VOUT pin and stops the switching operations, which protects poststate devices from overvoltage. Also, the VOUT state is notified by the PG pin.

When the output voltage rises to the OVP falling threshold (P_{GOVPLH}) for the output voltage setting or higher, the PG voltage is fixed to the low level. The IC becomes the OVP status, and the switching operations of the high-side FETs are stopped. When the output voltage once again falls to the OVP falling threshold (P_{GOVPHL}) for the output voltage setting or lower, the IC is released from the OVP state and resumes the switching operations. The PG voltage is fixed to the high level again.

Output Over Current Protection (Output OCP)

The output OCP is the function that limits the excessive current load and protects poststage devices.

Thermal Shutdown (TSD)

The TSD is the function that protects the IC from heat-destruction. When the junction temperature reaches +165°C (Typ), the high-side and low-side switching FET are turned off and the IC becomes the TSD status. When the junction temperature once again falls to +155°C (Typ) or lower, the IC is released from the TSD state and restarts the power supply.

^{*2:} The electrical characteristic is ensured by statistical characterization and indirect tests.



8.2 Protection Function Table

The following table shows the state of each pin when each protection function operates.

Table 8-1 Protection Function Table

Function	ENA Pin Setting	PG Pin Output	DC/DC Converter Operation	Remarks
Shutdown operation	L	Hi-Z (*1)	Shutdown	It is recommended to connect PG pin to VCC pin or VOUT pin via a pull-up resistor. When setting ENA pin to a low level, both VCC pin and VOUT pin voltage drop to 0V. Therefore, PG pin outputs 0V.
Nominal operation	Н	Hi-Z (*1)	Switching	-
Input under voltage protection (Input UVLO)	Н	L	Shutdown	After releasing UVLO state, this IC is automatically reset with soft start.
Output under voltage protection (Output UVP)	Н	L	Switching	-
Output over voltage protection (Output OVP)	Н	L	Shutdown	-
Output over current protection (Output OCP)	Н	L	Switching	OCP operates to drop the output voltage.
Thermal shutdown (TSD)	Н	L	Shutdown	After releasing TSD state, this IC is automatically reset with soft start.

^{*1:} PG pin is formed as an open drain structure. The internal MOSFET is in the OFF state.



9. Application Circuit Example and Parts list

Figure 9-1 Application Circuit Example

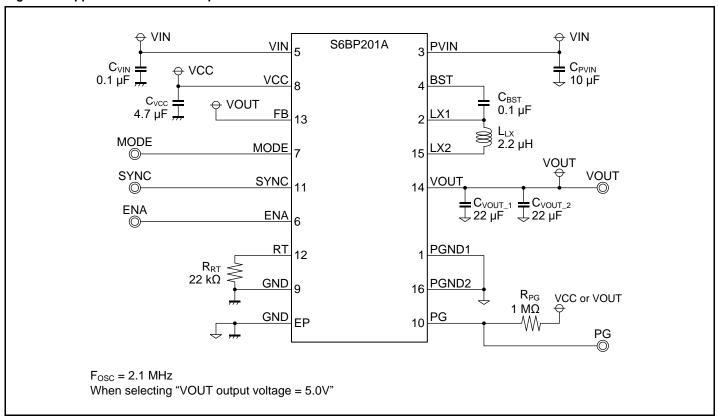


Table 9-1 Parts List

Symbol	Item	Value	Part Number	Vendor	Package Size (W×L×H[mm])	Remarks
C _{VIN} , C _{BST}	Ceramic capacitor	0.1 μF	CGA2B3X7R1H104K050BB	TDK	1.0×0.5×0.5	X7R, Rated Voltage: 50 Vdc
C _{PVIN}	Ceramic capacitor	10 μF	CGA9N3X7R1H106K230KB	TDK	5.7×5.0×2.3	X7R, Rated Voltage: 50 Vdc
C _{VCC}	Ceramic capacitor	4.7 µF	CGA4J3X7R1C475K125AB	TDK	2.0×1.25×1.25	X7R, Rated Voltage: 16 Vdc
Cvout_1, Cvout_2	Ceramic capacitor	22 µF	CGA6P1X7R1C226M250AC	TDK	3.2×2.5×2.5	X7R, Rated Voltage: 16 Vdc
L _{LX}	Inductor	2.2 µH	CLF7045T-2R2N-D	TDK	7.2×6.9×4.5	DCR: 14.6 mΩ, I _{DC_MAX} : 5.5A
R _{RT}	Resistor	22 kΩ	RK73H1JTTD2202F	KOA	0.8×1.6×0.45	ı
R _{PG}	Resistor	1 ΜΩ	RK73H1JTTD1004F	KOA	0.8×1.6×0.45	-

TDK: TDK Corporation KOA: KOA Corporation



10. Application Note

10.1 Setting the Operation Conditions

Operation State of DC/DC Convertor

The operation stage of DC/CD converter is set by both MODE pin and SYNC pin.

Table 10-1 Operation State of DC/DC Convertor

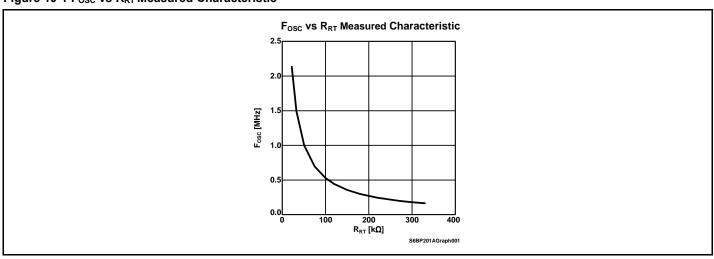
MODE Pin	SYNC Pin (Signal Input)	Operation State of DC/DC Convertor
	L (*3)	Automatic PWM/PFM switching operation from an internal clock
		Fixed PWM operation with synchronizing signal from an external clock (*2)
	H (*4)	Prohibition of use (*1)
	L (*3)	Fixed PWM operation from an internal clock
H (*4)	External clock input (*5)	Fixed PWM operation with synchronizing signal from an external clock (*2)
	H (*4)	Prohibition of use (*1)

^{*1:} When setting SYNC pin to a high level, the quiescent current (IVINQ) is increased.

Setting of Switching Frequency (Internal Clock)

The switching frequency (internal clock) can be set by RT resistor, which value is the timing resistance (R_{RT}), connected to RT pin. Set the timing resistance in a range within the following graph.

Figure 10-1 Fosc vs R_{RT} Measured Characteristic



The reference value can be calculated by the following formula.

$$F_{OSC}~[Hz] \approx \frac{1}{R_{RT} \times 21.7 \times 10^{-12}}$$

Fosc : Switching frequency [Hz] R_{RT} : Timing resistance [Ω]

^{*2:} Set the timing resistance (R_{RT}) to 330 k Ω .

^{*3:} Apply the GND1 or GND2 voltage.

^{*4:} Apply the VOUT voltage.

^{*5:} Apply the VOUT voltage at a high level. Apply the GND1 or GND2 voltage at a low level



Setting of Soft-start Time

The Soft-start time is determined by the timing resistance (RRT), the value of the resistor connected to RT pin.

$$T_{SS} [s] = \frac{1}{F_{OSC}} \times 2 \times 1024$$

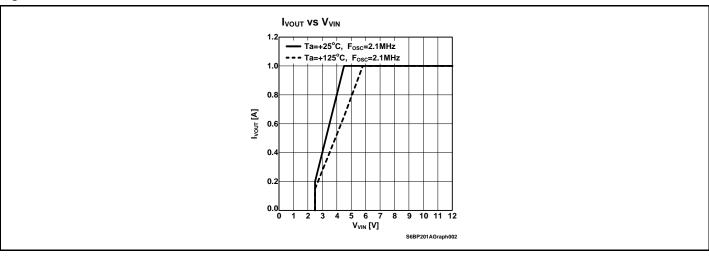
T_{SS} : Soft-start time [s]

Fosc : Switching frequency [Hz]

Consideration of VOUT Maximum Output Current

Make sure the VOUT maximum output current in a range within the following graph.

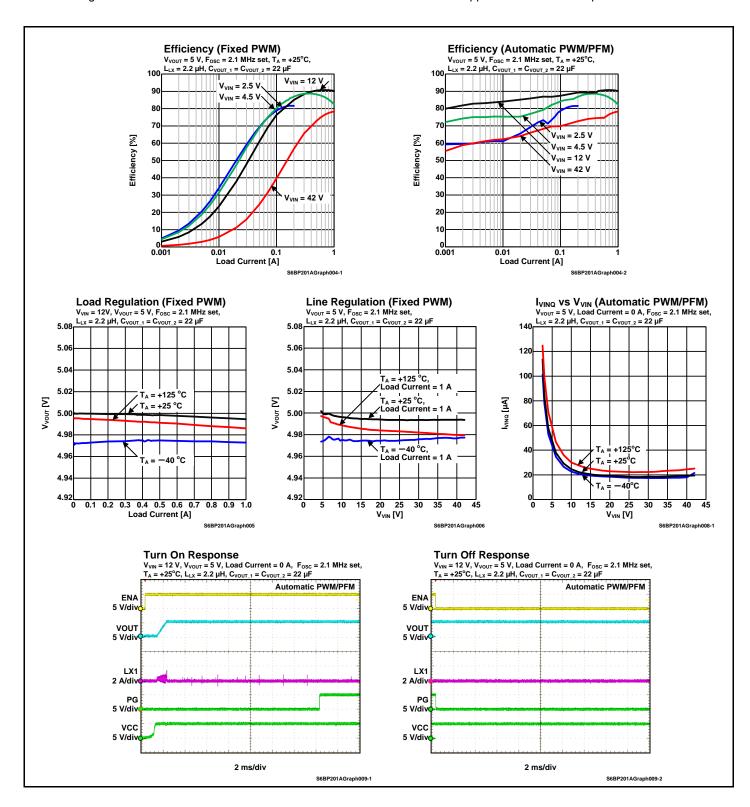
Figure 10-2 IVOUT VS VVIN



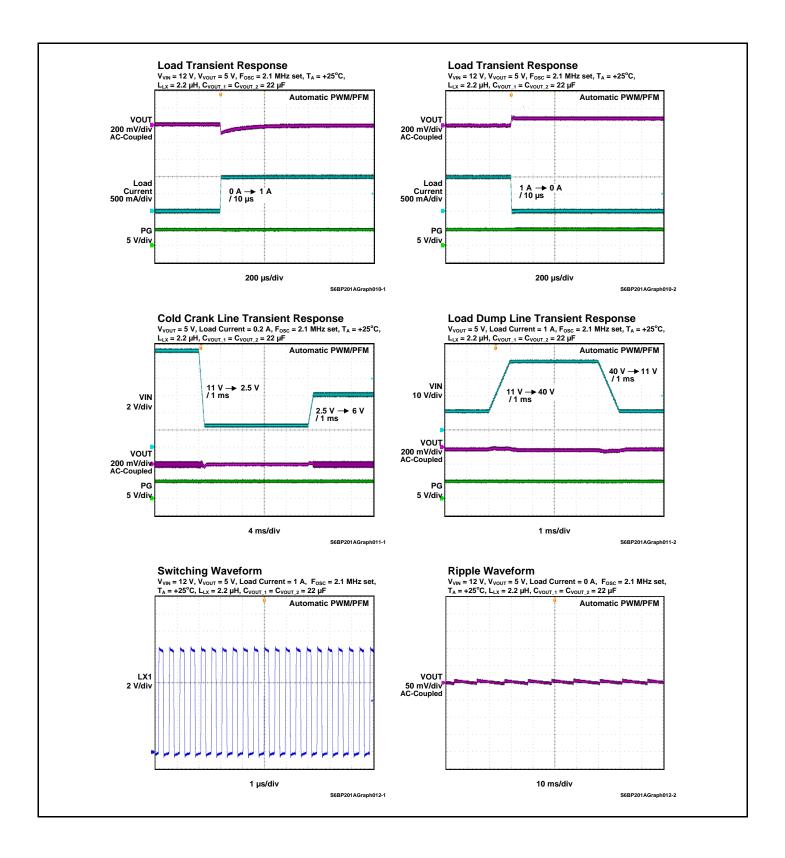


11. Reference Data

The followings are the reference data measured under the conditions shown in "9. Application Circuit Example and Parts list".









12. Usage Precaution

Printed circuit board ground lines should be set up with consideration for common impedance.

Take appropriate measures against static electricity.

- □ Containers for semiconductor materials should have anti-static protection or be made of conductive material.
- □ After mounting, printed circuit boards should be stored and shipped in conductive bags or containers.
- □ Work platforms, tools, and instruments should be properly grounded.
- \square Working personnel should be grounded with resistance of 250 k Ω to 1 M Ω in serial body and ground.

Do not apply negative voltages.

The use of negative voltages below -0.3V may make the parasitic transistor activated to the LSI, and can cause malfunctions.

13. RoHS Compliance Information

This product has observed the standard of lead, cadmium, mercury, Hexavalent chromium, polybrominated biphenyls (PBB), and polybrominated diphenyl ethers (PBDE).

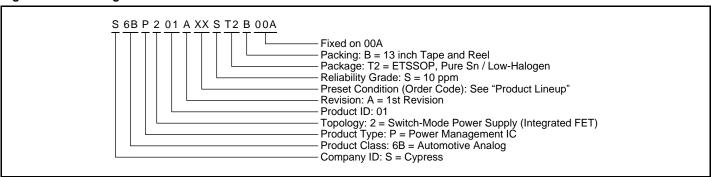
14. Ordering Information

Table 14-1 Ordering Information

Order Code	Part Number (MPN) (*1)	Package
1A	S6BP201A1AST2B00A	Digatio ETCCOD16 (0.65 mm nitch), 16 nin
4A	S6BP201A4AST2B00A	Plastic ETSSOP16 (0.65 mm pitch), 16-pin (Package Code: SEC016)
7A	S6BP201A7AST2B00A	(Fackage Code. SEC010)

MPN: Marketing Part Number

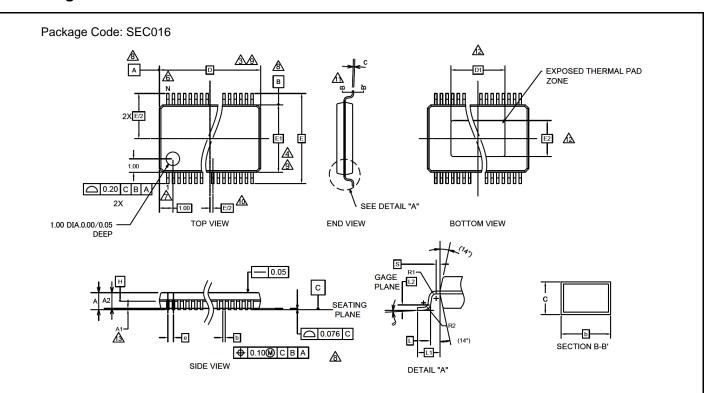
Figure 14-1 Ordering Part Number Definitions



^{*1:} Please contact our sales division for the part numbers (refer to "1. Product Lineup") not mentioned in this table.



15. Package Dimensions



	DII	DIMENSIONS					
SYMBOL	MIN.	NOM.	MAX.				
Α	-	-	1.10				
A1	0.05	- 1	0.15				
A2	0.85	0.90	0.95				
D	4.90	5.00	5.10				
E1	4.30	4.40	4.50				
E	6.40 BSC						
D1	2.90	3.00	3.10				
E2	2.90	3.00	3.10				
s	0.20	ı	ı				
R1	0.09	1	-				
R2	0.09	ı	ı				
θ	0°	ı	8°				
С	0.09	ı	0.20				
b	0.19	ı	0.30				
L	0.50	0.60	0.70				
L 1	1.00 REF						
L 2	0.25 BSC						
е	0.65 BSC						
N	16						

NOTE:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING & TOLERANCES PER ASME. Y14.5M-1994.
- ⚠ DIMENSION 'D' DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
- A DEMENSION 'E1' DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
- ⚠ DIMENSION 'b' DOES NOT INCLUDE DAMBER PROTRUSION.ALLOWABLE DAMBER PROTRUSIONS SHALL BE 0.07mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBER CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHOULD BE 0.08mm FOR 0.65mm PITCH, 0.08mm FOR 0.50mm PITCH AND 0.07mm FOR 0.40mm PITCH PACKAGES.
- M'I' IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH
- \triangle TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- ⚠ DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS 'D' AND 'E1' TO BE DETERMINED AT DATUM PLANE H.
- \hbar THIS DIMENSION APPLIES ONLY TO VARIATIONS WITH AN EVEN NUMBER OF LEADS PER SIDE FOR VARIATION WITH AN ODD NUMBER OF LEADS PER SIDE, THE "CENTER" LEAD MUST BE COINCIDENT WITH THE PACKAGE CENTERLINE, DATUM A.
- /1\CROSS SECTION B-B' TO BE DETERMINED AT 0.10 TO 0.25MM FROM THE LEAD TIP.
- DIMENSIONS "D1" AND "E2" ARE THERMALLY ENHANCED VARIATIONS.
 END USER SHOULD VERIFY AVAILABLE SIZE OF EXPOSED PER FOR SPECIFIC DEVICE APPLICATION "D1" AND "E2" DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- $\sqrt{3}$ A1 IS DEFINED AS THE VERTICAL CLEARANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

PACKAGE OUTLINE, 16 LEAD ETSSOP SEC016

002-10769 Rev. **



16. Major Changes

Spansion Publication Number: S6BP201A DS405-00032

Page	Section	Change Results				
Preliminary 0.1						
-	-	Initial release				
Preliminary 0.2						
12	10. Electrical Characteristics	"(TSD)" was added in the table of "10. Electrical Characteristics ".				

NOTE: Please see "Document History" about later revised information.

Document History

Document Title: S6BP201A, ASSP, 42V, 1A, Synchronous Buck-boost DC/DC Converter IC

Document Number: 002-08537

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	-	HIXT	09/04/2015	New Spec.
*A	5056149	HIXT	12/18/2015	Added Block Diagram Added Figure 15-1 Updated 16. Package Dimensions
*B	5164343	HIXT	03/08/2016	Added "AEC-Q100 compliant (Grade-1)" in Features Added Figure 3-1 I/O Pin Equivalent Circuit Diagram The followings in 7. Electrical Characteristics were updated. The parameter name of I _{VOUT} was changed from "VOUT output voltage" to "Maximum output current" The max values of I _{VOUT} were moved to the min column. Added 11. Development Support Added 12. Reference Data Deleted the ES part number from Table 15-1
*C	5909405	HIXT	10/13/2017	Adapted the Cypress new logo. Updated to the Cypress naming and format Updated "TSSOP" → "ETSSOP" in Features, Table 14-1 and Figure 14-1 Updated 15. Package Dimensions Added More Information Deleted "11. Development Support" (Moved to More Information) Changed the suffix of the Part Number from "000" to "00A" in 1. Product Lineup, Table 14-1 and Figure 14-1



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